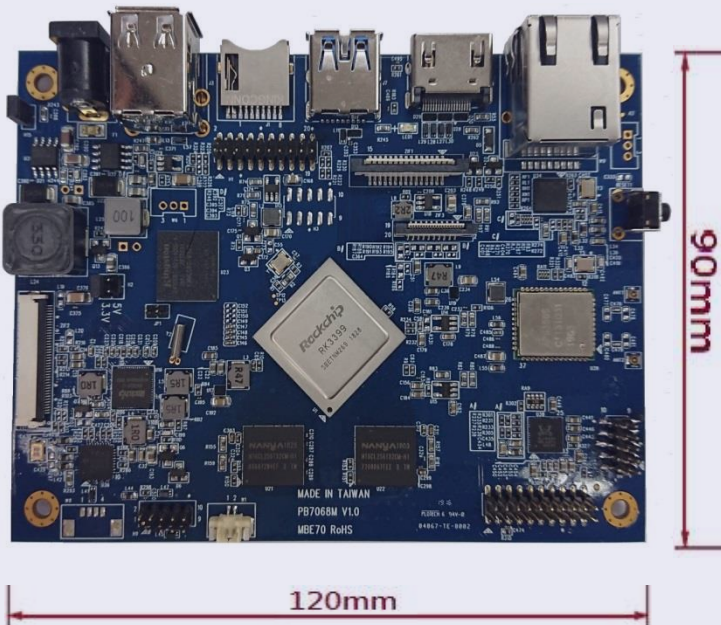


Motherboard with Dual Cortex-A72 + Quad Cortex-A53 core



Ordering Information

Part number : MBE70xyz

- **x:** The type of Processor
 - “ ” = Commercial version.
 - “K” = Industrial version.
- **y:** The DDR3 Memory size on board
 - “1” 1GB of DDR3.
 - “2” 2GB of DDR3.
- **z:** The eMMC size on board
 - “4” 4GB of eMMC.
 - “8” 8GB of eMMC.
 - “A” 16GB of eMMC.

Features

- **Processor:**
 - 、 High performance Dual Cortex-A72 @2.0Ghz + Quad Cortex-A53 @ 1.5Ghz
- **System Memory & Storage:**
 - 、 1 or 2GB DDR3-1066 SDRAM onboard
 - 、 4GB/ 8GB eMMC Flash memory
- **Multi-Media Processor:**
 - 、 ARM Mail-T860MP4 (GPU), AFBC supported
 - 、 Provides OpenGL ES1.1/2.0/3.0/3.1, OpenVG1.1, OpenCL, DX11
 - 、 Video Decoder:
H.264/H.265, 10bit, up to 4Kx2K@60fps,
VP9, 8bit, up to 4Kx2K@60fps,
MPEG-4/MPEG-2/VP8 up to 1080p@60fps
 - 、 Video Encoder:
H.264/MVC/VP8 encoders by 1080p@30fps
- **External I/O (On board side):**
 - 、 1 x Gigabit Ethernet port
 - 、 1 x HDMI® V2.0, 4Kx2K @60fps, HDCP2.x
 - 、 1 x eDP 1.3, 2 lane , 1080p@60fps, ZIF
 - 、 1 x USB 3.0, type A port
 - 、 2 x USB 2.0, type A port
 - 、 1 x Micro SD/SDHC card slot
 - 、 1 x Power Jack
- **Internal I/O**
 - 、 WLAN, 802.11 (a/b/g/n/ac, 2Tx2R) + Bluetooth (4.1 LE)
 - 、 Audio Combo Header, (Mic_in, Line_out, Spk_out, HP_out, SPDIF)
 - 、 MIPI-CSI, ZIF connector
 - 、 LCD Backlight control wafer
 - 、 PCAP touch panel wafer
 - 、 USB 2.0 (x 3) expansion header
 - 、 ADC, I2C, SPI, DIO extension header
 - 、 MEMS Combo header
 - 、 RS232 console wafer
- **Power supply:**
 - 、 Adaptor DC12V/ 24V
 - 、 PD board for PoE IEEE 802.3at (option)
- **Operation Temperature:**
 - Commercial version: 0°C to 60°C
 - Industrial version :-20°C to 60°C
- **Operating System:**
 - 、 Android 6.0/ 7.0
 - 、 Linux 4.4.154 _Debian 9.0 (Stretch)

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